



Material Content Data Sheet



Sales Product Name		TLE8108EM		Issued		20. July 2018		
MA#		MA000969214						
Package		PG-SSOP-24-4		Weight*		150.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.956	1.96	1.96	19620	19620
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8927	
wire	non noble metal	copper	7440-50-8	54.617	36.25	37.19	362490	371975
	noble metal	gold	7440-57-5	0.575	0.38	0.38	3817	3817
	encapsulation	organic material	carbon black	1333-86-4	0.174	0.12		1155
encapsulation	plastics	epoxy resin	-	8.003	5.31		53119	
	inorganic material	silicondioxide	60676-86-0	78.817	52.31	57.74	523103	577377
leadfinish	non noble metal	tin	7440-31-5	2.947	1.96	1.96	19561	19561
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1555	1555
glue	plastics	epoxy resin	-	0.230	0.15		1524	
	noble metal	silver	7440-22-4	0.689	0.46	0.61	4571	6095
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com